

## ABSTRACT OF THE DISCLOSURE

5 An electronic circuit module formed of an antenna coil and an  
integrated circuit provided on a circuit board is provided inside a hollow  
resin case formed of a first part and a second part. A first slit leading into  
the hollow portion is provided in one side face of the resin case formed of the  
first and second parts joined to each other. Since the electronic circuit  
10 module is not exposed to high temperatures and high pressure during the  
manufacturing process, defects such as the breakage of the integrated circuit  
or the disconnection of the antenna coil can be avoided. Since the slit  
leading into the hollow portion is provided, the hollow portion does not swell  
by the temperature increase. In addition, pinholes do not tend to be formed  
during the joining of the first and second parts. Thus, a contactless data  
15 carrier with an excellent electrostatic withstand voltage characteristic can be  
provided.